

D I C E N T R A S C H E M A T I C S

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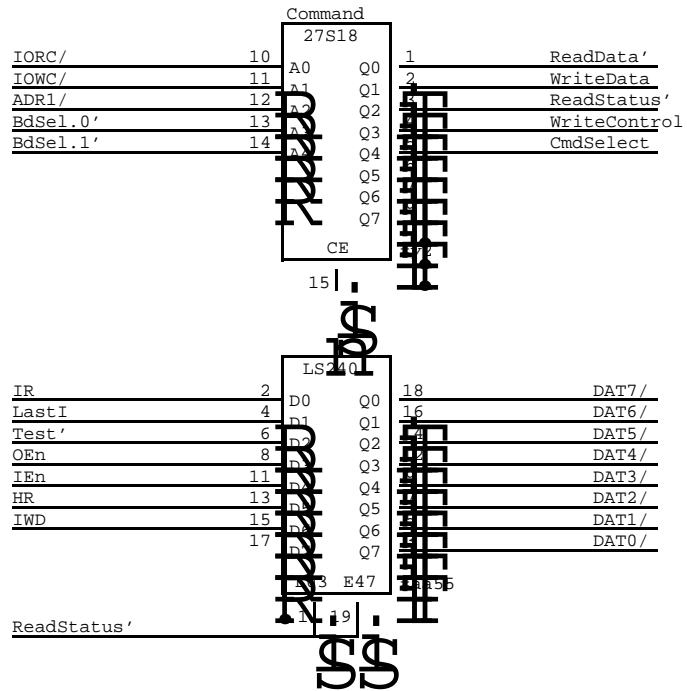
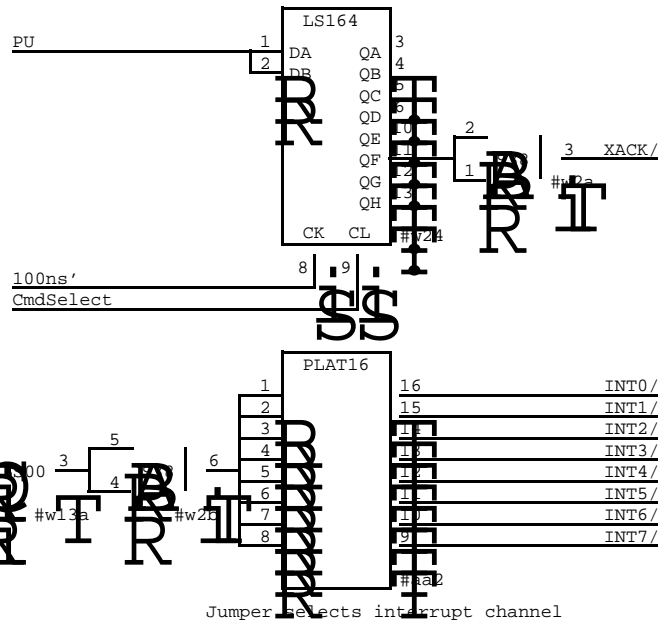
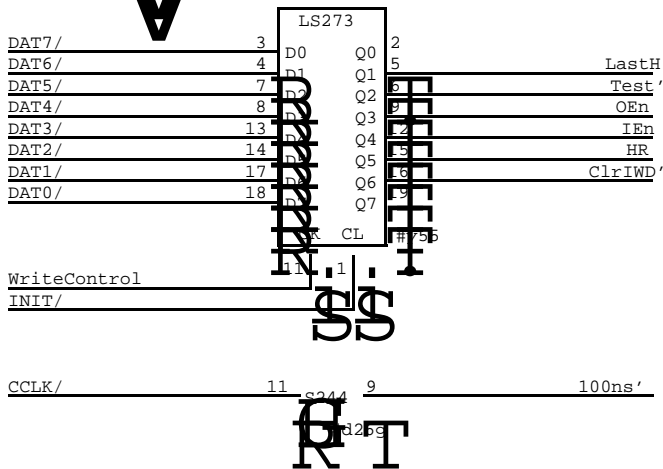
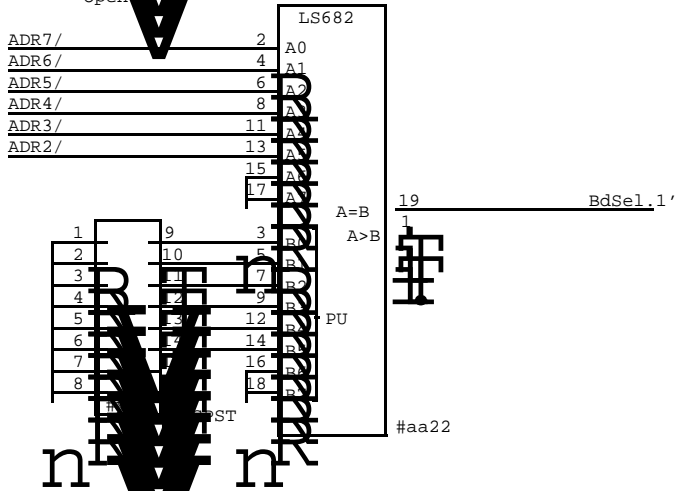
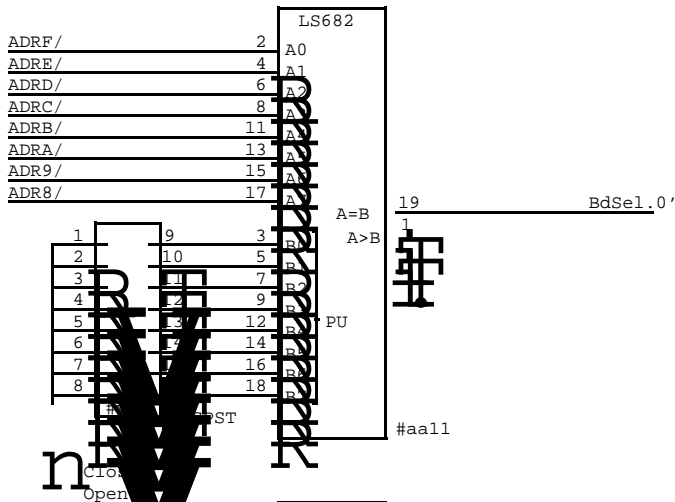
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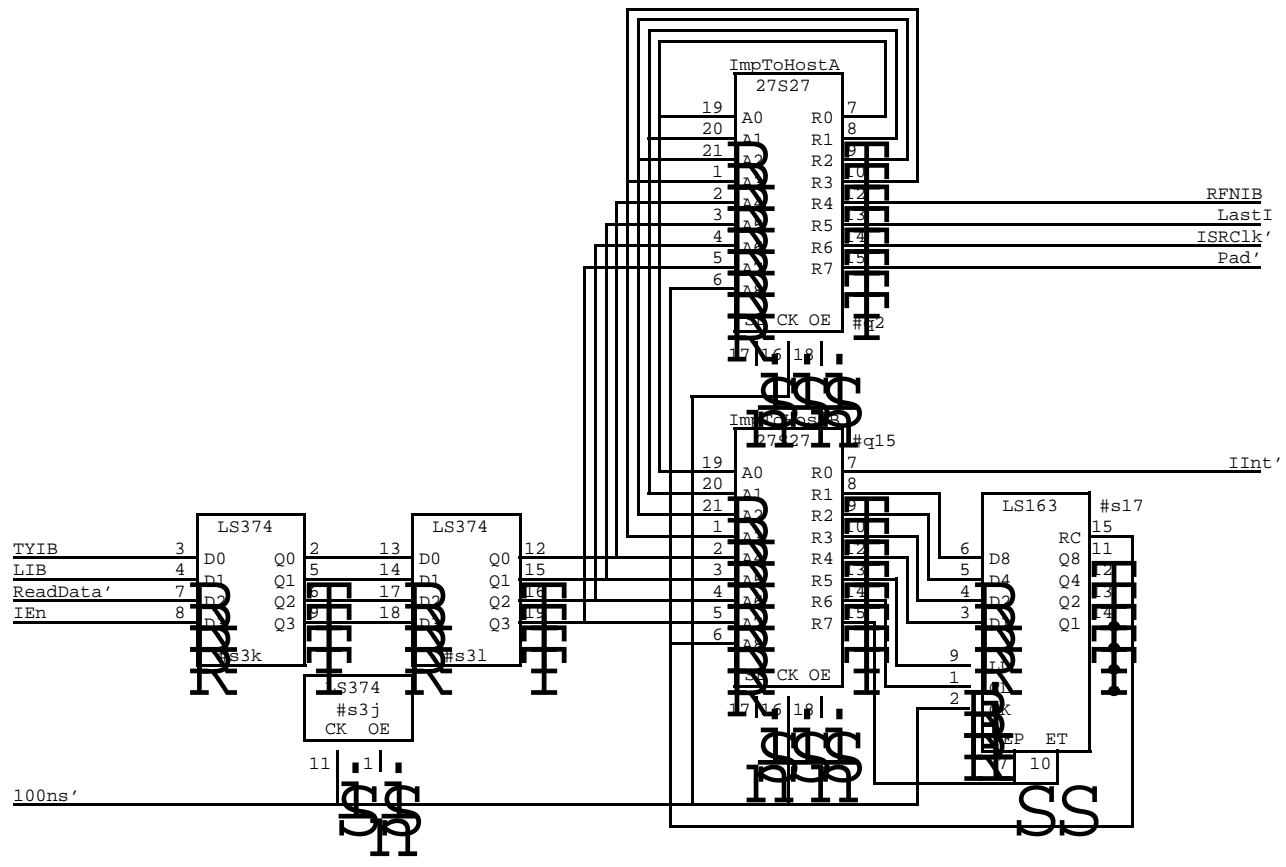
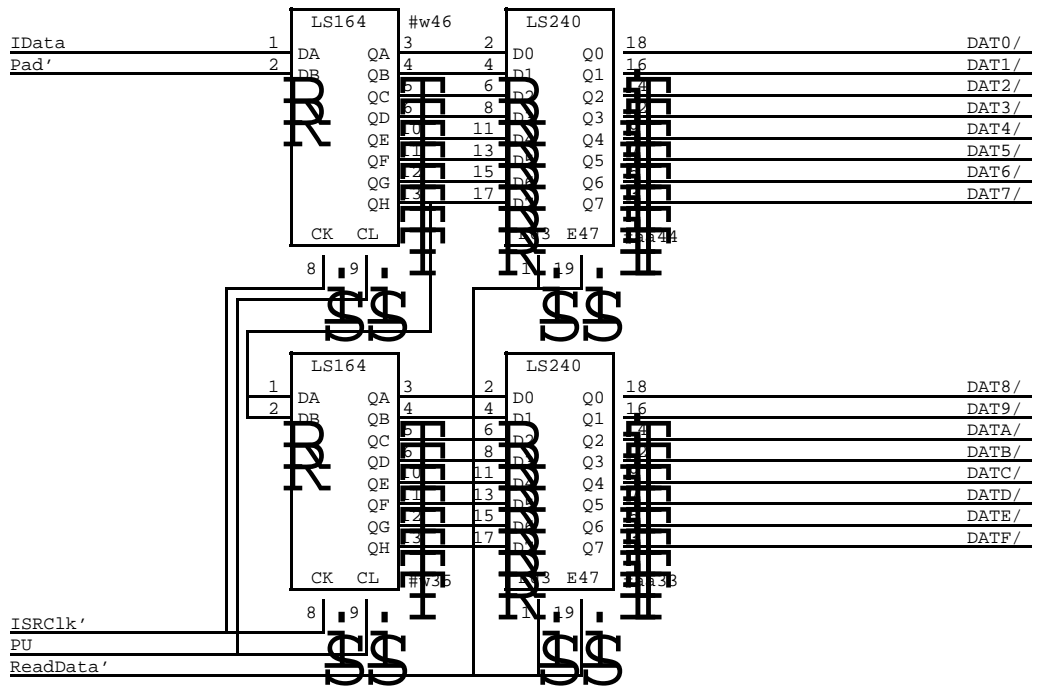
These drawings use the following [SIL] User.cm parameters:

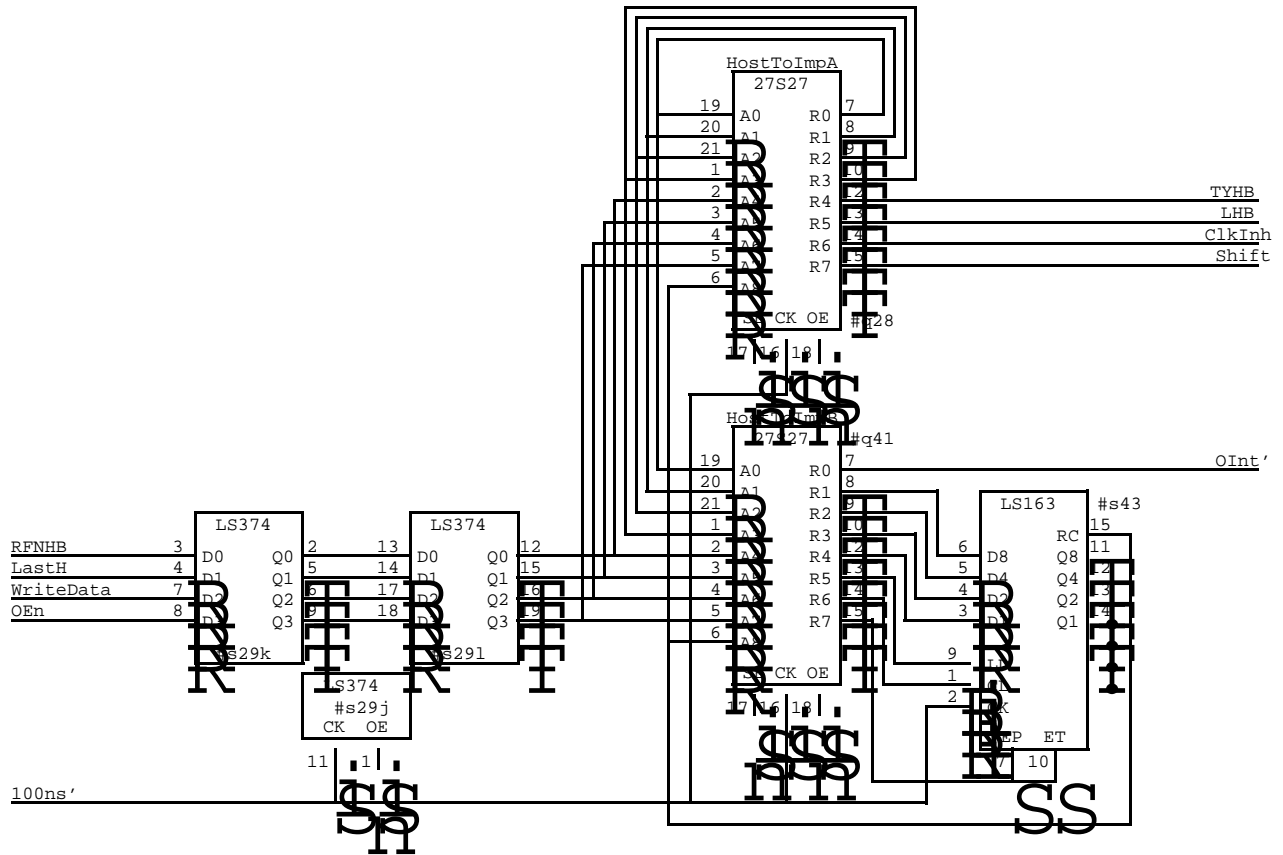
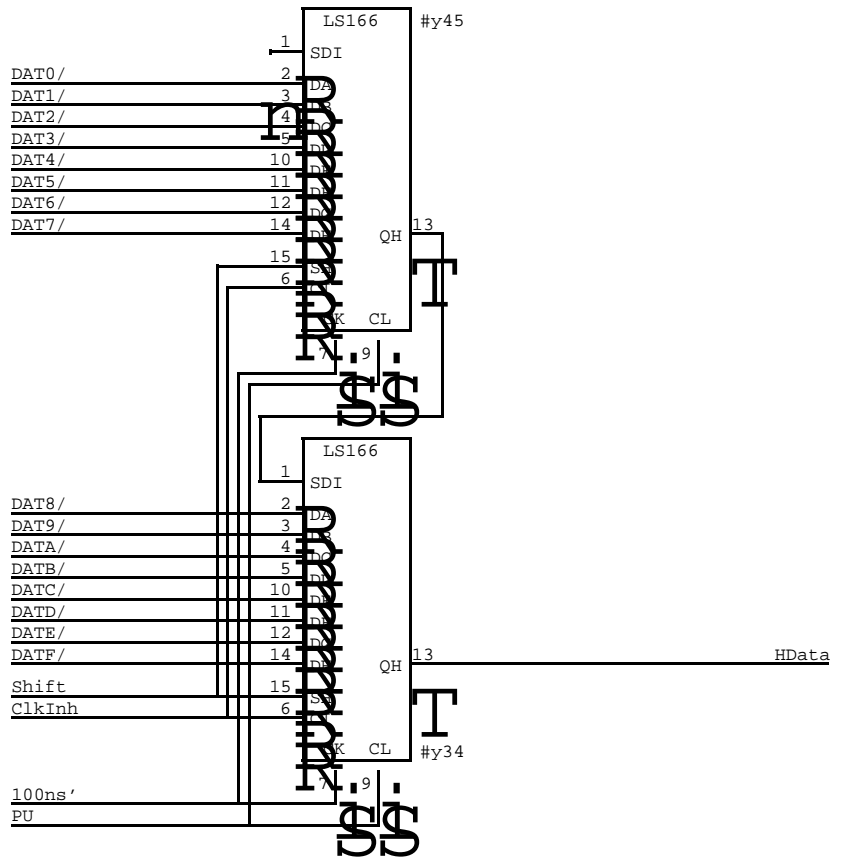
0: Helvetica10
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5: Dicentra.lb5
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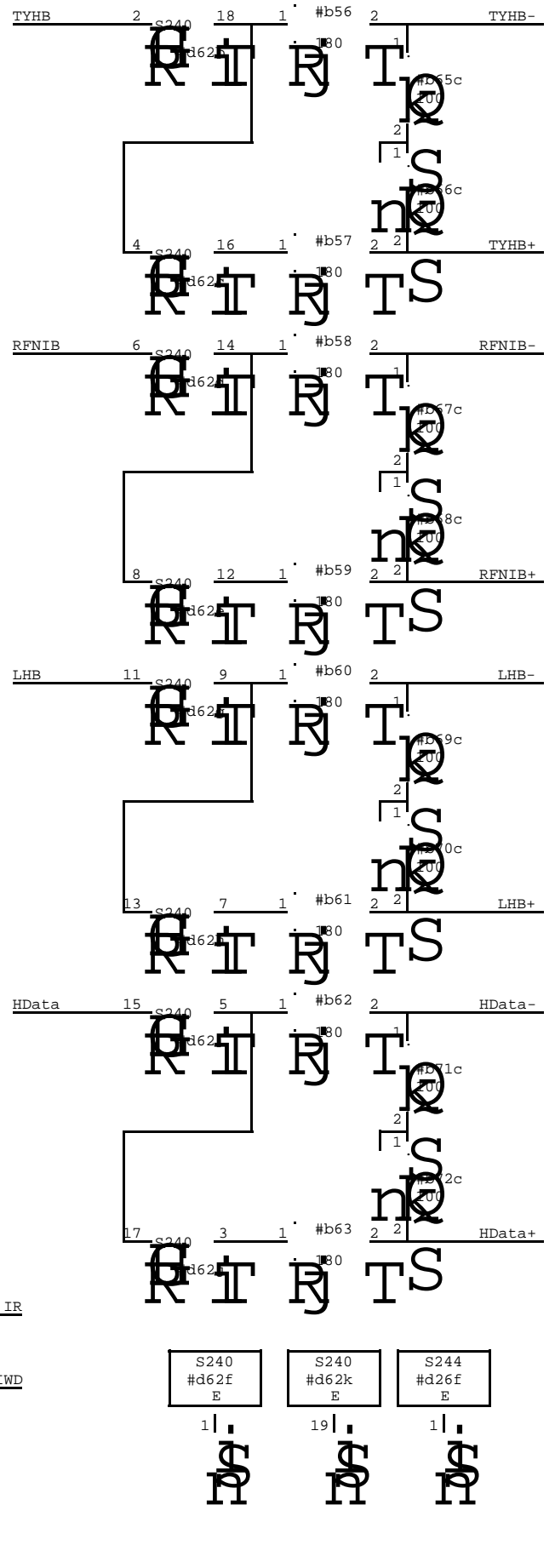
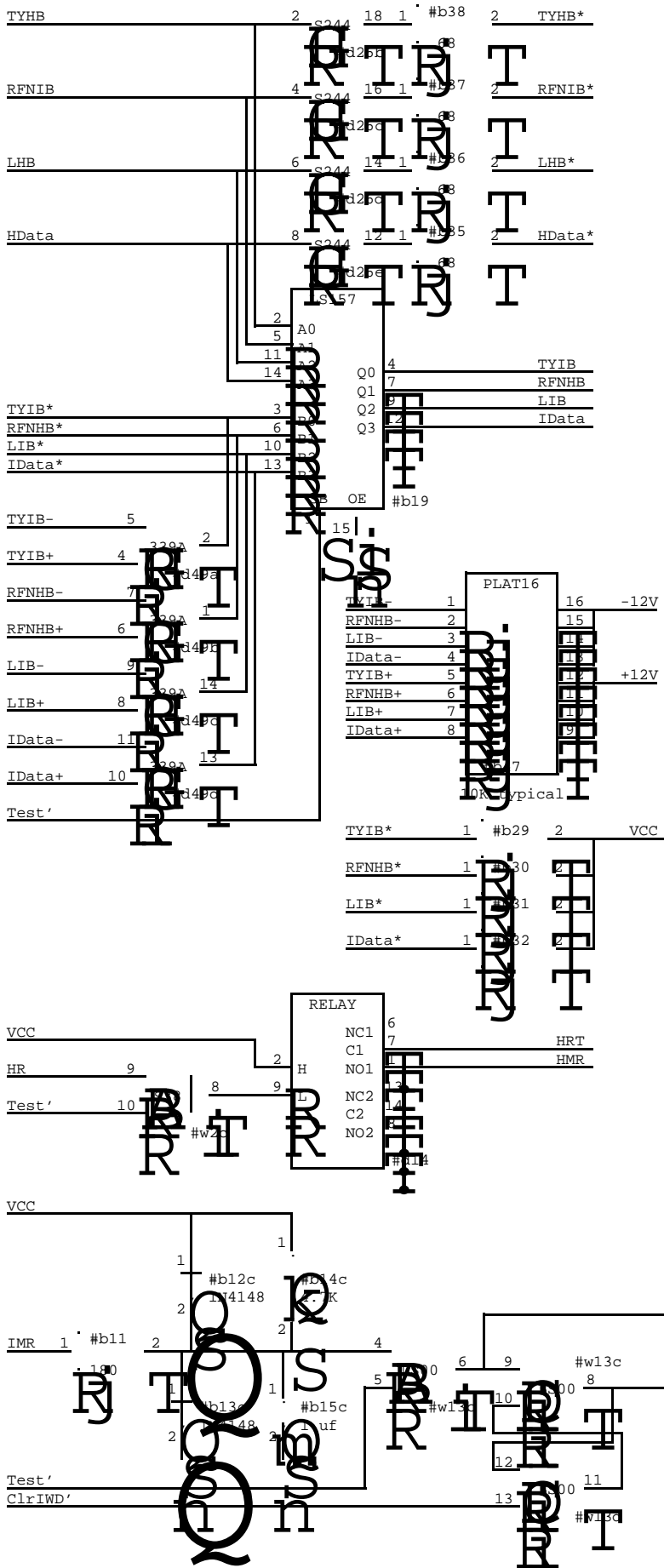
All files are kept on [Indigo]<Dicentra>

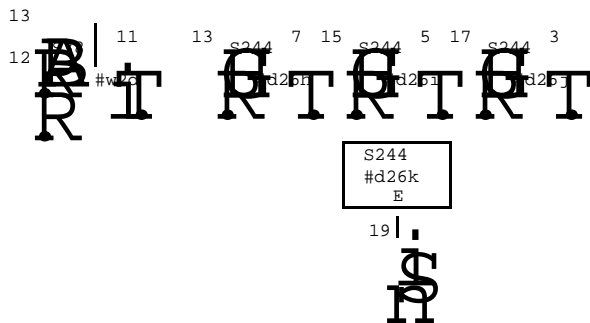
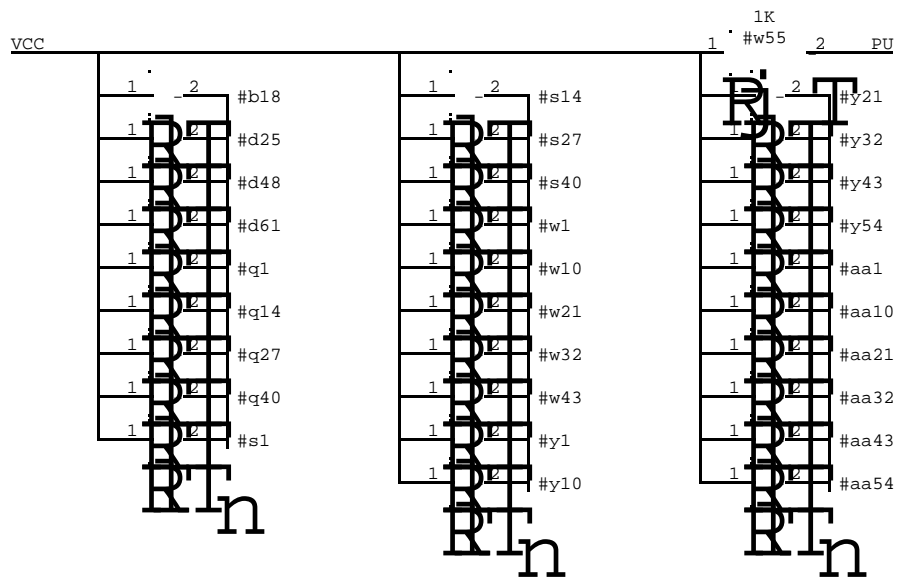
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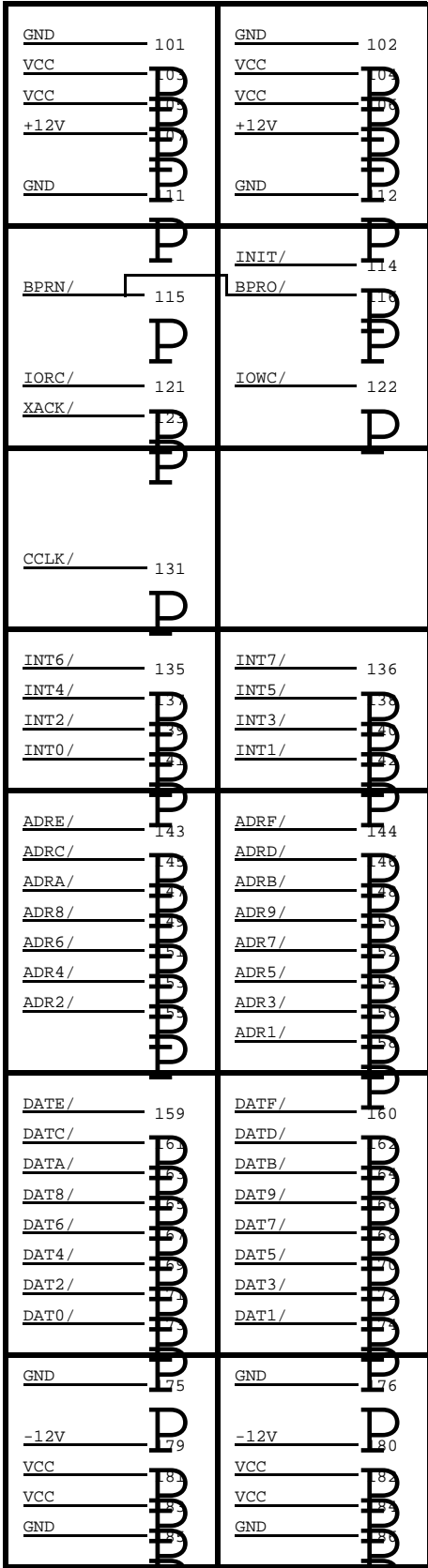




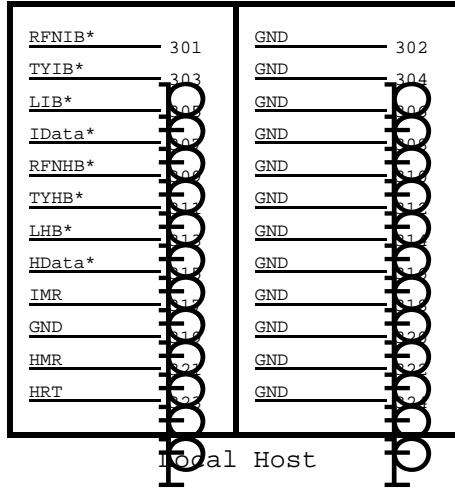




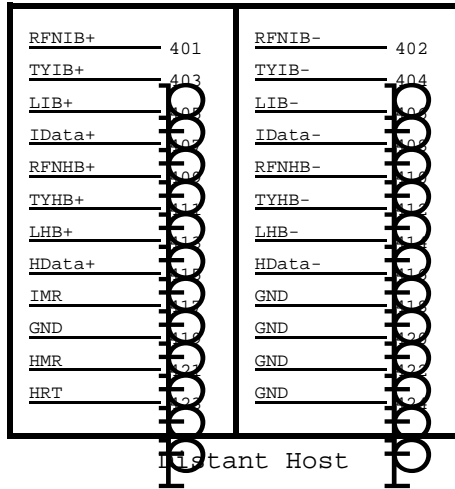




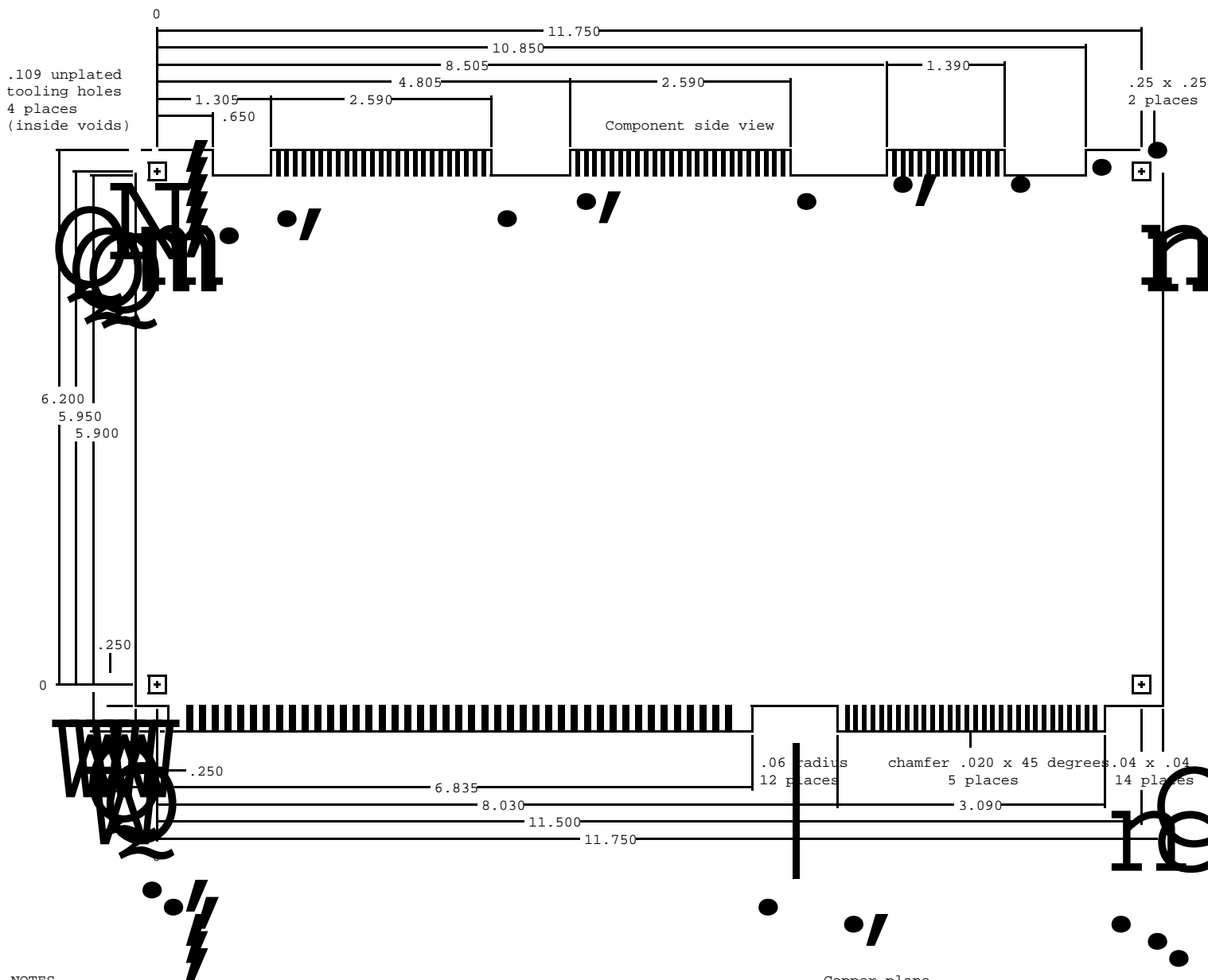
Multibus P1



Local Host



Distant Host



NOTES

- 1 All dimensions are in inches; drawing is not to scale.
X.XXX is +/- .005; X.XX is +/- .01.
- 2 Except as noted, this printed board shall be made in accordance with IPC-ML-910 Class II.
- 3 Acceptability of the finished board will be judged in accordance with IPC-A-600.
- 4 Base material: 1 oz Cu on FR4 in accordance with IPC-L-130.
- 5 Bonding agent: prepreg B-stage in accordance with IPC-L-110.
- 6 Solder mask: green epoxy in accordance with IPC-SM-840.
- 7 Silk screen: none
- 8 Plating: .000050 Au over .000200 Ni on contact fingers.
- 9 Plating: .001 Sn-Pb over .0010 Cu in holes and on traces.
- 10 Holes: 4 unplated holes, finished diameter .109.
- 11 Holes: xx unplated holes, finished diameter .031.
- 12 Plating: .05 components, connectors, and feedthrus.
- 13 Conductors: .010 wide, .010 spacing.



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| Project | Reference | File | Drawn by | Rev | Date | Page |
| PARC | Dicentra | DArpa08.sil | David Boggs | A | 8/22/83 | 08 |
| Fabrication Drawing | | | | | | |

